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S. DEPARTMENT OF COMMERCE
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

ISHIMURA, Hiroki
TAKAHASHI, Katsunori
SAKAMOTO, Mitsuru
ASARI, Naohito

8.25.03

2. Name and address of receiving party(ies)

Name: (1) **RENESAS TECHNOLOGY CORPORATION**

Street Address: (1) 4-1, Marunouchi 2-chome, Chiyoda-ku,
Tokyo, Japan

Name: (2) **RENESAS NORTHERN JAPAN SEMICONDUCTOR**

Street Address: (2) 1007-39, Izumisawa, Chitose-shi,
Hokkaido, Japan

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: **June 9, 23, 2003.**

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____.

A. Patent Application No.(s)

10/417,092 Filed April 17, 2003

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Antonelli, Terry, Stout & Kraus, LLP**

Internal Address:

**1300 North Seventeenth Street
Suite 1800
Arlington, VA 22209
USA**

City: State: Zip:

6. Total number of applications and patents involved **1**

7. Total fee (37 CFR 3.41)..... **\$ 40.00**

☒ Enclosed

☒ Authorized to be charged to deposit account

8. Deposit account number:

01-2135

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Alan E. Schiavelli, Reg#32,087

08/25/2003

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: **2**

Mail documents to be recorded with required cover sheet information to:
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PATENT
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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp.
and Renesas Northern Japan Semiconductor, Inc.
corporations organized under the laws of Japan,
located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan
and 1007-39, Izumisawa, Chitose-shi, Hokkaido, Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp.
and Renesas Northern Japan Semiconductor, Inc.
their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp. and Renesas Northern Japan Semiconductor, Inc.
their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp. and Renesas Northern Japan Semiconductor, Inc.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) <u>Hiroki Ishimura</u>	<u>6/23/2003</u>
2) <u>Katsunori Takahashi</u>	<u>6/9/2003</u>
3) <u>Mitsuru Sakamoto</u>	<u>6/9/2003</u>
4) <u>Asari Naohito</u>	<u>6/9/2003</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____